APPARATUS, METHOD AND COMPUTER PROGRAM PRODUCT FOR FAST SIMULATION OF MANUFACTURING EFFECTS DURING INTEGRATED CIRCUIT DESIGN

ABSTRACT OF THE DISCLOSURE

Methods, apparatus and computer program products provide a fast and accurate model for simulating the effects of chemical mechanical polishing (CMP) steps during fabrication of an integrated circuit by generating a design of an integrated circuit; while generating the design of the integrated circuit, using a simplified model to predict at least one physical characteristic of the integrated circuit which results from a CMP processing step to be used during manufacture of the integrated circuit, wherein the simplified model is derived from simulations performed prior to the design generation activities using a comprehensive simulation program used to model the physical characteristic; predicting performance of the integrated circuit using the predicted physical characteristic; and adjusting the design of the integrated circuit in dependence on the performance prediction.

Figure 4